

● PASTFACE

I should like to express my deep appreciation to many people who have kept helping me also in the preparation of this book "The Defects and Causes of Electronic Circuit Boards" in succession to the first and the revised editions of "The Defects and Causes of Printed Boards". I am heavily indebted to the people in Sony Corporation who were with the Editorial Committee of the revised edition above and have made great contributions as a user. Many companies deserve my appreciation for their submission of the photos used in this book.

JPCA-Japan Electronics Packaging and Circuits Association

JSIC Corp.

Airex Inc.

Ryowa Co., Ltd.

China Circuit Technology Corporation

Sony Corp.

Santa Lightmetals Industries Ltd.

Daeduck Electronics Co., Ltd.

Samsung Electro-Mechanics Co., Ltd.

Yamagishi-AIC Inc.

Hitachi Chemical Company, Ltd.

Hitachi AIC Inc.

I am pleased to be able to address that this book is more enriched in the content and has a wider scope of applications than preceding editions which is a result of the cooperation of Japan Electronics Packaging and Circuit Association and Sony Corporation working closely with me in the Editorial Committee organized for this document. As stated in the preface, since the product coverage has been getting broader in this book, I encourage you to make more effective and better use of this book.

I wish to thank sincerely Mr. Wu Yao Hui Mr. Lin Cheng Chuan Mr. Chen Han Zhen Mr. KOBAYASHI, Tadashi and Dr. SHIBATA, Akikazu for their works in translation of this book to Chinese and English.

Please do not hesitate to fill Questionnaire Sheet attached in the next page with your comment and to send it back to me.

June 2008 **Kenichi Hasegawa**